**InGaAs Selective Etch Rate**

**DSA**

**Checklist**

# Prepare

**☐** Login to iLabs to begin sessions

# pre etch with HCL

**☐** Pour enough HCL(1:3) to submerge samples into a beaker

**☐** submerge each sample for 30 seconds then rinse with DI water and dry with N2

# dissolve DSA

**☐** Prepare 250 mL DI water into 1000 mL beaker with stir bar

**☐** Gradually add in 25 g DSA

**☐** Bring solution to 50º C by setting hotplate temperature to about 85º C

**☐** Use magnetic stir bar to ensure dissolution of succinic acid

**☐** Keep solution on hotplate to prevent precipitation

# complete preparing etch solution

**☐** The current recipe is 250 mL DI water, 25 g succinic acid, and 10 mL hydrogen peroxide H2O2. Add ammonium hydroxide NH4OH2 to bring the pH to 5. (The DI water and succinic acid is already prepared at this step)

**☐** Complete etches in 5 minute intervals

**☐** Cleanup/ record data/ sign out of iLabs/ turn off nitrogen to the benches